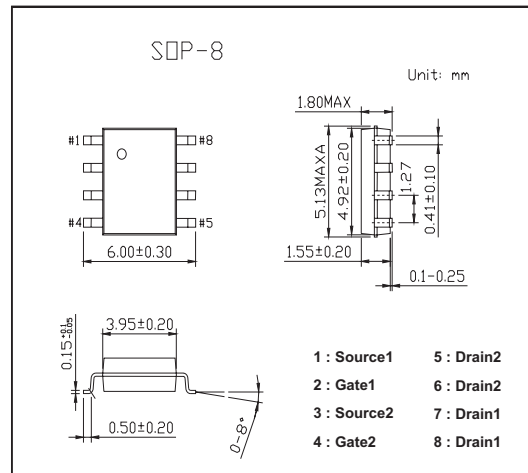
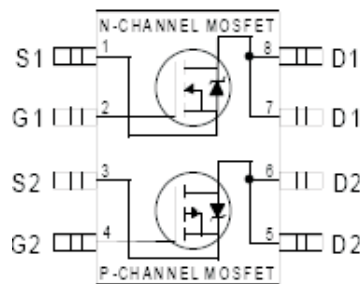


HEXFET[®] Power MOSFET

KRF9952

■ Features

- Generation V Technology
- Ultra Low On-Resistance
- Dual N and P Channel MOSFET
- Surface Mount
- Very Low Gate Charge and Switching Losses
- Fully Avalanche Rated



■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V_{DS}	30		V
Gate-to-Source Voltage	V_{GS}	± 20		V
Continuous Drain Current, $V_{GS} @ 10V @ T_a = 25^\circ\text{C}$	I_D	3.5	-2.3	A
Continuous Drain Current, $V_{GS} @ 10V @ T_a = 70^\circ\text{C}$	I_D	2.8	-1.8	
Pulsed Drain Current *1	I_{DM}	16	-10	
Continuous Source Current (Diode Conduction)	I_S	1.7	-1.3	A
Power Dissipation @ $T_a = 25^\circ\text{C}$	P_D	2		W
Power Dissipation @ $T_a = 70^\circ\text{C}$		1.3		
Single Pulse Avalanche Energy	E_{AS}	44	57	mJ
Avalanche Current	I_{AR}	2.0	-1.3	A
Repetitive Avalanche Energy	E_{AR}	0.25		mJ
Peak Diode Recovery dv/dt *2	dv/dt	5.0	-5	V/ns
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to + 150		$^\circ\text{C}$
Maximum Junction-to-Ambient *3	$R_{\theta JA}$	62.5		$^\circ\text{C}/\text{W}$

*1 Repetitive rating; pulse width limited by max. junction temperature.

*2 N-Channel $I_{SD} \leq 2.0\text{A}$, $di/dt \leq 100\text{A}/\mu\text{s}$, $V_{BD} \leq V_{(BR)DSS}$, $T_J \leq 150^\circ\text{C}$

P-Channel $I_{SD} \leq -1.3\text{A}$, $di/dt \leq 84\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq 150^\circ\text{C}$

*3 Surface mounted on FR-4 board, $t \leq 10\text{sec}$.

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■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250 μA	N-Ch	30			V
		V _{GS} = 0V, I _D = -250 μA	P-Ch	-30			
Breakdown Voltage Temp. Coefficient	ΔV _{(BR)DSS} /ΔT _J	I _D = 1mA, Reference to 25°C	N-Ch		0.015		V/°C
		I _D = -1mA, Reference to 25°C	P-Ch		0.015		
Static Drain-to-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 2.2A*1	N-Ch		0.08	0.10	Ω
		V _{GS} = 4.5V, I _D = 1.0A*1			0.12	0.15	
Static Drain-to-Source On-Resistance	R _{DS(on)}	V _{GS} = -10V, I _D = -1.0A*1	P-Ch		0.165	0.250	Ω
		V _{GS} = -4.5V, I _D = -0.5A*1			0.290	0.400	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	N-Ch	1.0			V
		V _{DS} = V _{GS} , I _D = -250 μA	P-Ch	-1.0			
Forward Transconductance	g _{fs}	V _{DS} = 15V, I _D = 3.5A*1	N-Ch		12		S
		V _{DS} = -15V, I _D = -2.3A*1	P-Ch		2.4		
Drain-to-Source Leakage Current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V	N-Ch			2.0	μA
		V _{DS} = -24V, V _{GS} = 0V	P-Ch			-2.0	
		V _{DS} = 24V, V _{GS} = 0V, T _J = 125°C	N-Ch			25	
		V _{DS} = -24V, V _{GS} = 0V, T _J = 125°C	P-Ch			-25	
Gate-to-Source Forward Leakage	I _{GSS}	V _{GS} = ±20V	N-Ch			±100	nA
			P-Ch				
Total Gate Charge	Q _g	N-Channel I _D = 1.8A, V _{DS} = 10V, V _{GS} = 10V	N-Ch		6.9	14	nC
Gate-to-Source Charge	Q _{gs}	P-Channel	N-Ch		1.0	2.0	
			P-Ch		1.7	3.4	
Gate-to-Drain ("Miller") Charge	Q _{gd}	I _D = -2.3A, V _{DS} = -10V, V _{GS} = -10V	N-Ch		1.8	3.5	
			P-Ch		1.1	2.2	
Turn-On Delay Time	t _{d(on)}	N-Channel V _{DD} = 10V, I _D = 1.0A, R _G = 6.0 Ω	N-Ch		6.2	12	ns
Rise Time	t _r	R _D = 10 Ω P-Channel	N-Ch		8.8	18	
			P-Ch		14	28	
Turn-Off Delay Time	t _{d(off)}	V _{DD} = -10V, I _D = -1.0A, R _G = 6.0 Ω R _D = 10 Ω	N-Ch		13	26	
			P-Ch		20	40	
Fall Time	t _f		N-Ch		3.0	6.0	
Input Capacitance	C _{iss}	N-Channel V _{GS} = 0V, V _{DS} = 15V, f = 1.0MHz	N-Ch		190		pF
			P-Ch		190		
Output Capacitance	C _{oss}	P-Channel	N-Ch		120		
			P-Ch		110		
Reverse Transfer Capacitance	C _{rss}	V _{GS} = 0V, V _{DS} = -15V, f = 1.0MHz	N-Ch		61		
			P-Ch		54		
Continuous Source Current (Body Diode)	I _S		N-Ch			1.7	A
			P-Ch				
Pulsed Source Current (Body Diode) *2	I _{SM}		N-Ch			16	A
			P-Ch				

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■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Diode Forward Voltage	V _{SD}	T _J = 25°C, I _S = 1.25A, V _{GS} = 0V*3		0.82	1.2	V
		T _J = 25°C, I _S = -1.25A, V _{GS} = 0V*3		-0.82	-1.2	
Reverse Recovery Time	t _{rr}	N-Channel		27	53	ns
		T _J = 25°C, I _F = 1.25A, di/dt = 100A/μs*1	P-Channel		27	
Reverse RecoveryCharge	Q _{rr}	P-Channel		28	57	nC
		T _J = 25°C, I _F = -1.25A, di/dt = -100A/μs*1	P-Channel		31	

*1 Pulse width ≤ 300 μs; duty cycle ≤ 2%.

*2 Repetitive rating; pulse width limited by max. junction temperature.

*3 N-Channel Starting T_J = 25°C, L = 22mH R_G = 25 Ω, I_{AS} = 2.0A.

P-Channel Starting T_J = 25°C, L = 67mH R_G = 25 Ω, I_{AS} = -1.3A.